PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6496036

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SATOSHI HIROI	04/21/2009
YUKIO ICHIKAWA	04/21/2009
YUMI SATO	04/21/2009
MARIE SUZUKI	04/04/2009
YASUSHI NAKAJIMA	04/21/2009
HIROSHI NAGATANI	04/21/2009
MASAHIRO HARA	04/21/2009
HIROSHI HORIKI	04/21/2009
KOUHEI FUJIMOTO	04/21/2009
TAKESHI MATSUZAWA	04/23/2009
HIROYUKI MITSUBORI	04/22/2009
SAKAE HOUJOU	05/05/2009
MINGSHAN YANG	04/22/2009

RECEIVING PARTY DATA

Name:	SONY CORPORATION
Street Address:	1-7-1 KONAN, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	108-0075

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17145803

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	SONYJP 3.0-1906 CCCCC
NAME OF SUBMITTER:	MELINDA C. CORMIER
SIGNATURE:	/Melinda C. Cormier/
DATE SIGNED:	01/14/2021

Total Attachments: 8
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S09P0807US00
SONYJP 3.0-1906
Docket Number: ____________

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INFORMATION PROCESSING APPARATUS, INFORMATION PROCESSING METHOD, PROGRAM AND INFORMATION PROCESSING SYSTEM
for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 17/145,803, Filing Date: 01/11/2021.

This assignment executed on the dates indicated below.

Satoshi HIROI
Name of first or sole inventor — Execution date of U.S. Patent Application

Chiba, Japan
Residence of first or sole inventor

Satoshi Hiroi — April 21, 2009
Signature of first or sole inventor — Date of this assignment

Yukio ICHIKAWA

Name of second inventor Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Yukio Ichikawa April 21, 2009

Signature of second inventor Date of this assignment

Yumi SATO

Name of third inventor Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

Yumi Sato 4.21.2009.

Signature of third inventor Date of this assignment

Marie SUZUKI

Name of fourth inventor Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fourth inventor

Marie Suzuki 4.4.2009

Signature of fourth inventor Date of this assignment

Yasushi NAKAJIMA

Name of fifth inventor Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fifth inventor

Yasushi Nakajima April 21. 2009

Signature of fifth inventor Date of this assignment

Hiroshi NAGATANI

Name of sixth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of sixth inventor

Hiroshi Nagatani

Signature of sixth inventor

4. 21. 2009

Date of this assignment

Masahiro HARA

Name of seventh inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of seventh inventor

Masahiro Hara

Signature of seventh inventor

April 21, 2009

Date of this assignment

Hiroshi HORIKI

Name of eighth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of eighth inventor

Hiroshi Horiki

Signature of eighth inventor

April 21, 2009

Date of this assignment

Kouhei FUJIMOTO

Name of ninth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of ninth inventor

Kouhei Fujimoto

Signature of ninth inventor

april 21, 2009

Date of this assignment

Takeshi MATSUZAWA

Name of tenth inventor — Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of tenth inventor

Takeshi Matsuzawa — April 23, 2009

Signature of tenth inventor — Date of this assignment

Hiroyuki MITSUBORI

Name of eleventh inventor — Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of eleventh inventor

Hiroyuki Mitsubori — Apr. 22, 2009

Signature of eleventh inventor — Date of this assignment

Sakae HOUJOU

Name of twelfth inventor — Execution date of U.S. Patent Application

Tokyo, Japan

Residence of twelfth inventor

Signature of twelfth inventor — Date of this assignment

Mingshan YANG

Name of thirteenth inventor — Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of thirteenth inventor

Mingshan Yang — 04.22.2009

Signature of thirteenth inventor — Date of this assignment

S09P0807US00
SONYJP 3.0-1906
Docket Number: ___________

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INFORMATION PROCESSING APPARATUS, INFORMATION PROCESSING METHOD, PROGRAM AND INFORMATION PROCESSING SYSTEM for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: ____________________, Filing Date: ____________________.

This assignment executed on the dates indicated below.

Satoshi HIROI
Name of first or sole inventor   Execution date of U.S. Patent Application

Chiba, Japan
Residence of first or sole inventor

____
Signature of first or sole inventor   Date of this assignment

Yukio ICHIKAWA

Name of second inventor Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Signature of second inventor Date of this assignment

Yumi SATO

Name of third inventor Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

Signature of third inventor Date of this assignment

Marie SUZUKI

Name of fourth inventor Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fourth inventor

Signature of fourth inventor Date of this assignment

Yasushi NAKAJIMA

Name of fifth inventor Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fifth inventor

Signature of fifth inventor Date of this assignment

Hiroshi NAGATANI

Name of sixth inventor

Execution date of U.S. Patent Applicatio

Tokyo, Japan

Residence of sixth inventor

Signature of sixth inventor

Date of this assignmen

Masahiro HARA

Name of seventh inventor

Execution date of U.S. Patent Applicatio

Tokyo, Japan

Residence of seventh inventor

Signature of seventh inventor

Date of this assignment

Hiroshi HORIKI

Name of eighth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of eighth inventor

Signature of eighth inventor

Date of this assignment

Kouhei FUJIMOTO

Name of ninth inventor

Execution date of U.S. Patent Application

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Residence of ninth inventor

Signature of ninth inventor

Date of this assignment

Takeshi MATSUZAWA

Name of tenth inventor

Execution date of U.S. Patent Applicatio

Kanagawa, Japan

Residence of tenth inventor

Signature of tenth inventor

Date of this assignment

Hiroyuki MITSUBORI

Name of eleventh inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

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Signature of eleventh inventor

Date of this assignment

Sakae HOUJOU

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Execution date of U.S. Patent Application

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北條 栄枝

2009.5.5

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Date of this assignment

Mingshan YANG

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Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of thirteenth inventor

Signature of thirteenth inventor

Date of this assignment